

**PMP10155 Rev\_B BOM**

Count	RefDes	Value	Description	Size	Part Number	MFR
1	C17	0.22uF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
1	C12	10pF	Capacitor, Ceramic, 50V, NP0, 10%	603	Std	muRata
1	C9	2.2nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
3	C11 C13 C100	.1u	Capacitor, Ceramic, 16-V, [temp], [tol]	805	std	muRata
2	C16 C101	2.2uF	Capacitor, Ceramic, 16V, X5R, +/-10%	805	std	std
1	C2	10nF	Capacitor, Ceramic, 500V, X7R, 10%	1210	12107C103KAT2A	AVX
1	C8	1000pF Y1	Capacitor, Cer. Disc, 250V, Y1	0.394 X 0.315 inch Max.	ECK-ANA102MB	Panasonic
1	C3	0.15 uF	Capacitor, Film, 275VAC, 20%	0.689 x 0.217	ECQU2A154ML	Panasonic
1	C1	0.22 uF	Capacitor, Film, 275VAC, 20%	0.689 x 0.217	ECQU2A224ML	Panasonic
2	C4-5	3300 uF	Capacitor, Aluminum, SMT, 16V,	J16	EEVFK1C332M	Panasonic
1	C10	47uF	Capacitor, Aluminum, SM, ±20%, 35V,	D Code	EEEFK1V470P	Panasonic
1	C6	100uF	Capacitor, Aluminum, 25V, ±20%	0.328 x 0.328 inch	EEEFK1E101P	Panasonic
1	C7	47uF	Capacitor, Aluminum, 63V, ±20%	0.328 x 0.328 inch	EEEFK1J470P	Panasonic
1	D6	BAS16	Diode, Switching, 150-mA, 75-V, 350mW	SOT23	BAS16	Vishay-Liteon
3	D100-102	BAS16	Diode, Switching, 150-mA, 75-V, 350mW	SOT23	BAS16	Vishay
1	D13	BAW56	Diode, Dual , 250-mA, 75 V	SOT23	BAW56-TP	Micro Commercial Co
1	D1	DF06S	Bridge Rectifier, 600V, 1A, Glass Passivated, SMD	DF-S	DF06S	Diodes
2	D2-3	BYG10M	Diode, Standard Rectifier,1.5A, 1000V	SMA	BYG10M	Vishay
1	D11	MBR0520L	Diode, Schottky, 0.5A, 20V	SOD-123	MBR0520L	Fairchild
1	D9	MURA120T3	Diode, Rectifier, 1A, 200-V	SMA	MURA120T3	ON Semi
1	D7	MURA140T3	Diode, Rectifier, 1A, 400-V	SMA	MURA140T3	ON Semi
1	D4	US1K	Diode, 1-A, 800-V	SMB	US1K	Diodes Inc.
1	D5	8TQ100	Diode, Schottky, 8-A, 100-V	TO220AC	VS-8TQ100PBF	Vishay
1	D8	15V	Diode, Zener, 15-V, 8.5-mA, 225-mW, 5%	SOT23	MMBZ5245BLT1	ON Semi
1	D12	6.8V	Diode, Zener, 6.8-V, 20-mA, 225-mW, 5%	SOT23	MMBZ5235BLT1	ON Semi
1	F1	1A/250V	Fuse, TR5 Series, Time Lag, 250V	0.335	3721100041	Wickmann
1	L2	20mH	Inductor, 0.5 A, 540 milliohm	0.512 x 0.728 inch	744822120	WE
1	L1	1mH	Inductor, SMT, 0.8A, 2 ohm	0.51x 0.37 inch	DO3340P-105ML	Coilcraft
1	U3	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay
1	R17	0	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R104	100k	Resistor, Chip, 1/16W, 1%	603	Std	Std
4	R25-26 R28 R100	10k	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R11 R13	1K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R24	1k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R101	32.4k	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R12 R15	40.2K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R16 R102	10	Resistor, Chip, 1/10-W, 1%	805	Std	Std
2	R7 R18	10K	Resistor, Chip, 1/10W, yy%	805	Std	Std
1	R23	0.82	Resistor, Chip, 0.82-Ohms, 1-W, 1%	2512	Std	Std

2	R2-3	47K	Resistor, 47KOhm, 1W, 5%	2512	STD	STD
1	R103	220 Ohm	Resistor, Axial, ½ W, 1%	0.300 X 0.100 inch	STD	STD
1	R6	100K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R19	18K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R22	1k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R10	6.98K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R20-21	47.5K	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R8	2.2	Resistor, Chip, 1/10W, 5%	805	Std	Std
1	R5	0.03	Resistor, Chip, 1/2W, 1%	1210	STD	STD
2	R9 R14	1.5M	Resistor, Chip, ¼ W, 5%	1210	STD	STD
2	R1 R4	100K	Resistor, Chip, ¼ W, 5%	1210	STD	STD
1	J1	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	U1	TL103WID	IC, Dual Op Amp With Internal Reference	SO8	TL103WID	TI
2	TP1-2	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	Q2	STB7NK80ZT4	MOSFET, N-ch, 800-V, 5.2-A, 1.8 Ohm	SMD-220	STB7NK80ZT4	ST
1	Q3	3904	Bipolar, NPN, xx-V, yy-mA, zz-W	SOT23	MMBT3904	Std
1	Q1	PZT2222A	Bipolar, NPN, 40-V, 1000-mA, 1-W	SOT223	PZT2222A	Fairchild
1	U2	UCC28810D	IC, LED LIGHTING POWER CONTROLLER	SO8	UCC28810D	TI
1	T1	G154006LF	Transformer, Transition Mode Flyback, 760uH	1.122 x 1.200 inch	G154006LF	GCI Technologies

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